What is CRUVI?

A short overview

The word CRUVI is a combination of the Estonian word "KRUVI" for screw and the letter "C", which refers to the half of the hexagonal screw head. The "K" has been replaced by a "C" to emphasize the reference to the screw head. All modules are mechanically fixed with M2 screws with a diameter of 2 mm. The expansion bus interface is designed to create an open ecosystem of function modules for high-performance peripheral connectivity. Its main focus is on supporting FPGA and FPGA SoC devices from all major manufacturers.



Trenz Electronic GmbH

Company profile

- · Located in Germany
- Established 1992 as a sole proprietorship
- · 2002 converted to GmbH
- now with 90+ employees

· ISO 9001 certified SMD in-house production





The picture shows FMC to CRUVI-HS, Pmod to CRUVI-LS, CRUVI host with LS and HS slot and CRUVI LS modules. CRUVI fills the space between Pmod and FMC card, it can be smaller and cheaper than SYZYGY.

Trenz Electronic Production

- · 25 years of development with in-house production
- 50,000+ modules per year; 500,000 lifetime
- 500+ customizable modules
- Rugged design with long term supply guarantee
- Industrial temperatures

Trenz Electronic Services

- · Integration of FPGA and SoC modules
- Electronic Design Service
- Electronic Manufacturing Service
- Rapid prototyping
- · All modules are developed & manufactured in Germany

Contact us

for more information or custom solutions

Trenz Electronic GmbH

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Forging **FPGA** Frontiers

Development, Manufacturing and supply of FPGA & SoC Modules



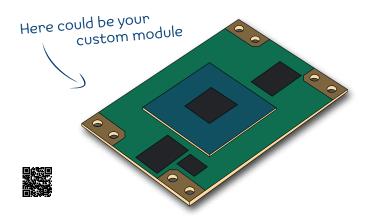
ELECTRONIC DESIGN SERVICE

- + Customizable
- + Rapid prototyping
- + Extended device life cycle
- + Rugged for industrial applications
- + Automotive grade available
- + Small and powerful
- + Cooling solutions
- + Baseboards/Starter Kits



Supply of FPGA & SoC Modules and customized turnkey solutions

Other assembly variants for cost or performance optimization available on request.



Modules with AMD FPGA

Modules with Altera® FPGA



SoM with 4x5cm form factor

Modules from **Trenz Electronic** with 4×5 cm form factor are fully mechanically and largely electrically compatible among each other.



All modules produced by **Trenz Electronic** are developed and manufactured in Germany.

Carrier Boards

for 4 x 5 cm and other different form factors

The carrier boards are baseboards for 4×5 SoMs, which exposes the modules B2B-connector-pins to accessible connectors & provides a whole range of on-board components to test & evaluate



The other carrier boards are baseboards for specific **Trenz Electronic** SoMs, which exposes the module's B2B-connector-pins to accessible connectors & provides a whole range of on-board components to test & evaluate **Trenz Electronic** SoMs.



Starter Kits

Pre-assembled and ready-to-use

In general our Starter Kits contain a **Trenz Electronic** micromodule with a pre-assembled heat sink mounted on a **Trenz Electronic** baseboard. The TE08xx series modules are build in a black Core V1 Mini-ITX enclosure. All this provided with a fitting power supply including different adapters, a microSD card, a USB cable plus srews and bolts. Different module variants can be integrated on request.





Cooling Solutionsfor Trenz Electronic Modules

The individual cooling solutions from **Trenz Electronic** are required for efficient and effective cooling of the modules and serve to ensure the long-term functional reliability of the systems. The product portfolio includes both – active and passive cooling solutions.





e.g. KK0835-03

e.g. 34314

We are offering different customized cooling solutions for a selection of modules.

